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| -   | 41  | "air egress" and adhesive                                  | USPAT;               | 2002/04/25 17:56 |
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| •   | 434 | "vacuum metallization"                                     | USPAT;               | 2002/04/25 17:56 |
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| -   | 10  | "vacuum metallization" and adhesive and (sticker or label) | USPAT;               | 2002/04/25 17:56 |
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| •   | 219 | "vacuum metallization" and adhesive                        | USPAT;               | 2002/04/26 12:13 |
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